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MOSFET – Power, N-Channel, SUPERFET[®] III, FAST 650 V, 95 mΩ, 30 A

NTHL095N65S3H

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET FAST series helps minimize various power systems and improve system efficiency.

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)} = 77 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 58 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 522 pF)
- 100% Avalanche Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

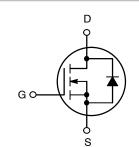
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar

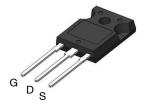


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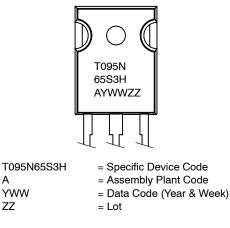
V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	95 mΩ @ 10 V	30 A





TO-247 Long Leads CASE 340CX

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage		650	V
V _{GSS}	Gate to Source Voltage	– DC	±30	V
		– AC (f > 1 Hz)	±30	
I _D	Drain Current	– Continuous (T _C = 25°C)	30	А
		– Continuous (T _C = 100°C)	18	
I _{DM}	Drain Current	– Pulsed (Note 1)	84	А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		284	mJ
I _{AS}	Avalanche Current (Note 2)		5.5	А
E _{AR}	Repetitive Avalanche Energy (Note 1)		2.08	mJ
dv/dt	MOSFET dv/dt		120	V/ns
	Peak Diode Recovery dv/dt (Note 3)	20		
P _D	Power Dissipation	(T _C = 25°C)	208	W
	– Derate Above 25°C		1.67	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		260	°C

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality shows be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. $I_{AS} = 5.5 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 15 \text{ A}$, di/dt $\le 200 \text{ A/}\mu\text{s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.60	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient, Max.	40	

PACKAGE MARKING AND ORDERING INFORMATION

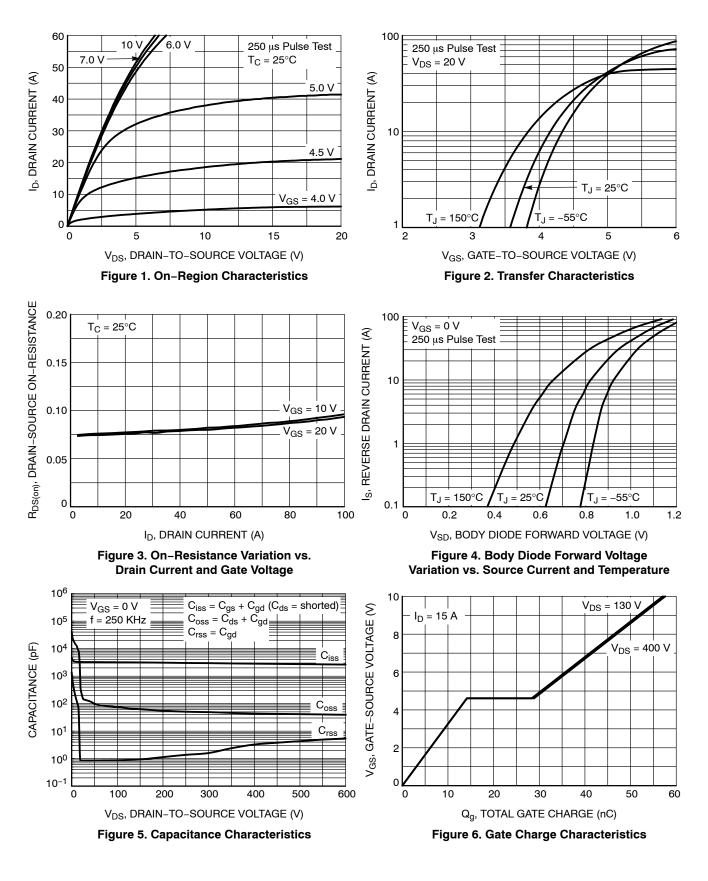
Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTHL095N65S3H	T095N65S3H	TO-247 (Pb-Free / Halogen Free)	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

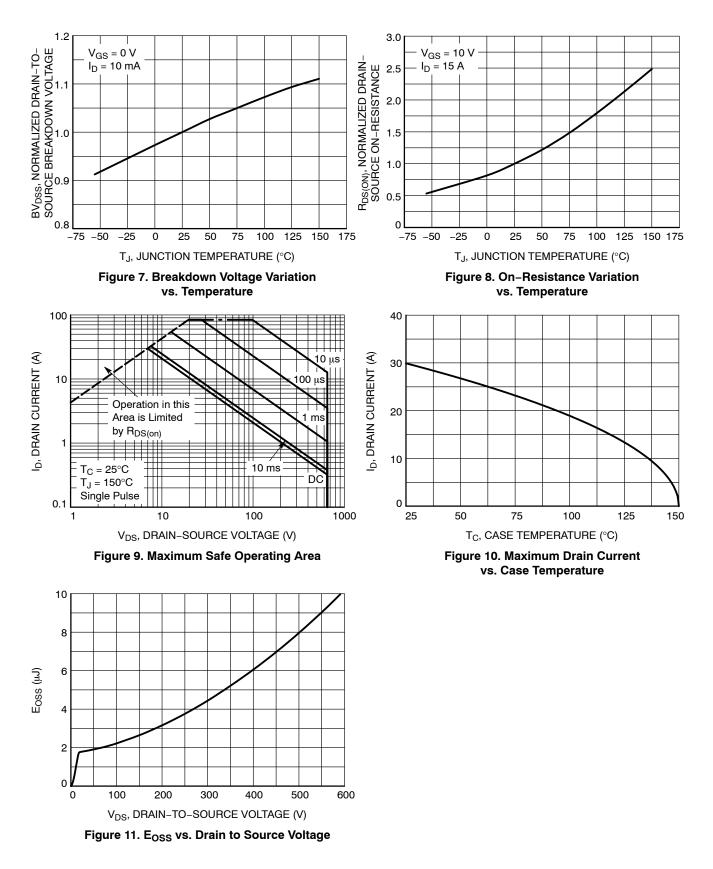
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS			-	•	
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	650	-	-	V
		V_{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 10 mA, Referenced to 25°C	_	0.63	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 650 V, V_{GS} = 0 V	-	-	1	μA
		V_{DS} = 520 V, T_C = 125°C	-	1.8	-	
I _{GSS}	$\label{eq:Gate to Body Leakage Current} V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$		-	-	±100	nA
ON CHARACTE	RISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 2.8$ mA	2.4	-	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 15 A	-	77	95	mΩ
9 _{FS}	Forward Transconductance $V_{DS} = 20 \text{ V}, I_D = 15 \text{ A}$		-	30	-	S
OYNAMIC CHA	RACTERISTICS					
C _{iss}	Input Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 250 kHz	-	2833	-	pF
Coss	Output Capacitance		-	43	-	pF
Coss(eff.)	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	522	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	75	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 15 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	58	-	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	-	14	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	15	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.2	-	Ω
WITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 15 \text{ A},$	-	24	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10 V, R _g = 4.7 Ω (Note 4)	-	7.4	-	ns
t _{d(off)}	Turn-Off Delay Time		-	69	-	ns
t _f	Turn-Off Fall Time		-	2.4	-	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS					
۱ _S	Maximum Continuous Source to Drain Diode Forward Current			-	30	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	84	Α
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 15 A	_	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 15 A,	-	367	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/µs	_	6.3	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)



TYPICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)



TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

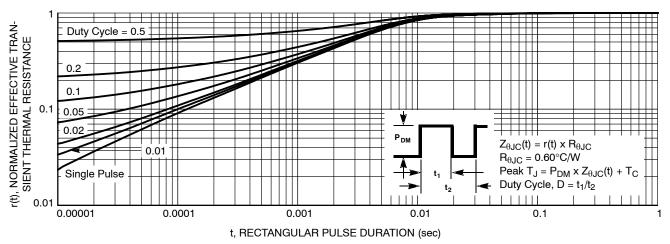


Figure 12. Transient Thermal Impedance

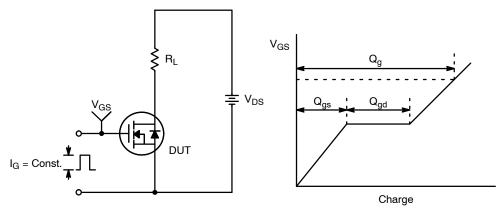


Figure 13. Gate Charge Test Circuit & Waveform

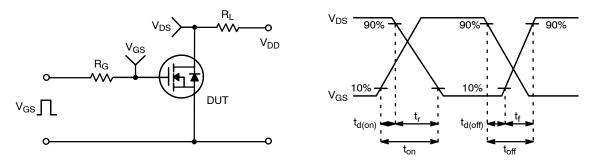


Figure 14. Resistive Switching Test Circuit & Waveforms

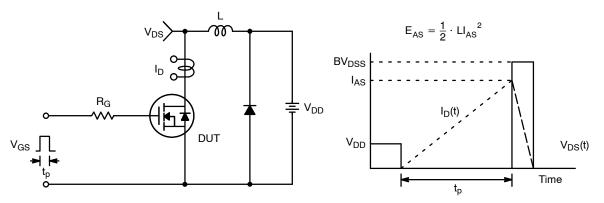


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

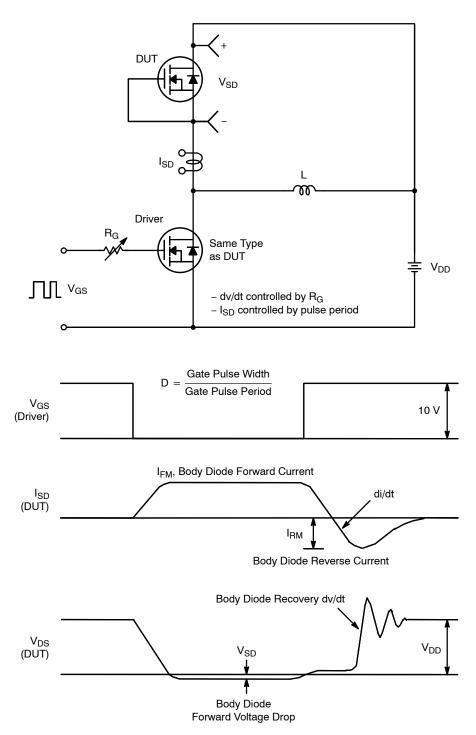
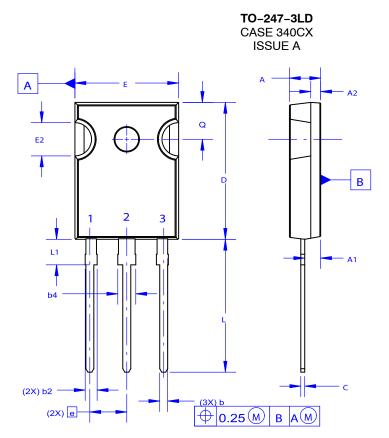


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

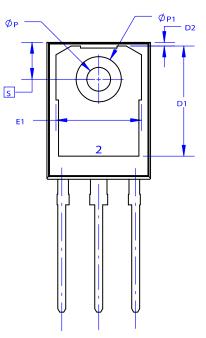
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PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
E	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
Ø P 1	6.60	6.80	7.00		

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